09/605293



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> One South Main Street, Suite 500 Dayton, Ohio 45402-2023

> > 937.223.2050 Fax | 937.223.0724 E-mail | kghs@kghs.com

> > > www.KGHS.com

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TO: Examiner N. Drew Richards, Art Unit 2815

Company: Assistant Commissioner for Patents

Fax No.: 703/872-9319

FROM: Julie G. Cope, Reg. No. 48,624/amm

Date: March 11, 2003

Pages: 17

(including cover page)

Our Docket No.: MIO 0037 VA

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2002/017 15/BHE Puble 3-18-03 4/30/3

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of

Applicant

: David L. Chapek

Serial No.

: 09/605,293

Filed

: June 28, 2000

Title

: SEMICONDUCTOR DEVICES INCLUDING A LAYER OF

POLYCRYSTALLINE SILICON HAVING A SMOOTH

MORPHOLOGY

Docket

: MIO 0037 VA

Art Unit

: 2815

CERTIFICATE OF FACSIMILE TRANSMISSION

Assistant Commissioner for Patents

Washington, DC 20231

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AMENDMENT AFTER FINAL

This paper is being filed in response to the Office Action mailed on December 16, 2002. Entry of this amendment is requested as it is believed the amendments and remarks place the application in condition for allowance or will at least reduce the number of issues for appeal.

CLEAN VERSION OF THE AMENDMENTS

A version of the amendments showing the markings is provided in a separate appendix attached to this paper.

In the Specification

At page 8, lines 2-13 should read:

With continued reference to Fig. 1, the layer 14 of silicon dioxide 16 is formed on the substrate 12 by an conventional oxidation process or deposition process, and has been doped with hydrogen ions to provide a surface conducive to the deposition of polycrystalline silicon. Depending upon the nature of the layer 14 of silicon dioxide 16, the layer 14 of silicon dioxide 16 can be formed by thermal oxidation, chemical vapor deposition (CVD), low pressure chemical vapor deposition (LPCVD), plasma enhanced